# **PATENT ASSIGNMENT COVER SHEET**

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3193492

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
JHON JHY LIAW	03/01/2013

### **RECEIVING PARTY DATA**

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.		
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park		
City:	Hsin-Chu		
State/Country:	TAIWAN		
Postal Code:	300-77		

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	13789090

## **CORRESPONDENCE DATA**

**Fax Number:** (972)732-9218

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 972-732-1001

Email:docketing@slater-matsil.comCorrespondent Name:SLATER & MATSIL, L.L.P.

Address Line 1: 17950 PRESTON RD., SUITE 1000

Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSM12-1102	
NAME OF SUBMITTER: LISETTE REYES-WASHINGTON		
SIGNATURE:	/Lisette Reyes-Washington/	
DATE SIGNED:	01/22/2015	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 1** 

source=TSM12-1102\_Assignment#page1.tif

PATENT 503146880 REEL: 034789 FRAME: 0781

ATTORNEY DOCKET NO. TSM12-1102

#### **ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

TITLE OF INVENTION	Dual-port SRAM Systems			
SIGNATURE OF INVENTOR AND NAME	Then Thy Land Jhon Jhy Liaw			
DATE	Mar. 1. >013			
RESIDENCE (City, County, State)	Zhudong Township, Taiwan			

TSM12-1102 Page 1 of 1 Assignment

PATENT REEL: 034789 FRAME: 0782